

## 10/100 PC CARD MAGNETIC MODULE

### MODEL NO.: HC-027

#### FEATURE:

**RoHS Compliant**

Do not use material and use that the prohibition that SS-00259 stipulates

RoHS peak solder rating 260°C / 3~5Sec

Designed to meet IR requirement

Meets IEEE802.3 Baseline Wander Compensation specification

Specifications @ 25°C

Operating temp : 0°C to +80°C

OCL : 350uH MIN.(100KHz,100mV)

Cw/w : 25 pF Max. (100KHz,100mV)

DCR (1-2 & 5-6 PIN) : 1.0 Ω Max

DCR (7-8 & 11-12 PIN) : 1.5 Ω Max.

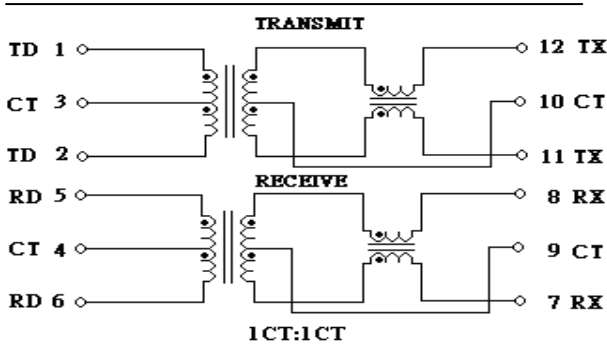
CASE Pin Surface plating : Sn Thickness 5 μm min.

HIPOT(VAC) : 1500 ( 60s / 10mA ) CHIP SIDE:(1-2-3)&(4-5-6) Short , LAN SIDE (7-8-9)&(10-11-12) Short

MSL=2

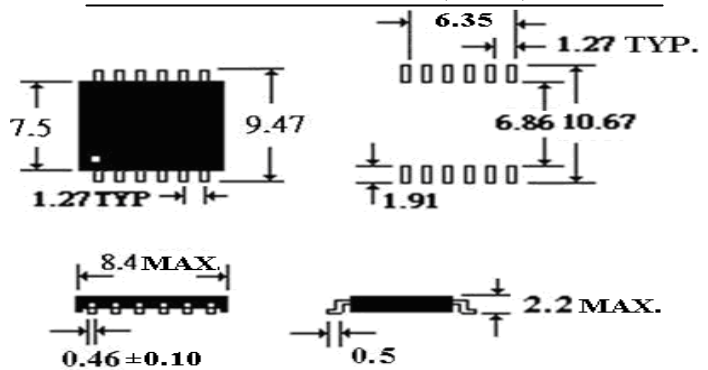
Part Number	Turns Ratio (±5%)	Insertion Loss (dB MIN)	Return Loss (dB MIN)		Common Mode Rejection Ratio (dB MIN.)		Cross Talk (dB MIN)	
			1~40 MHz	40~100 MHz	2 MHz	30-200 MHz	1 MHz	10~100 MHz
HC-027	TX/RX	0.1~125 MHz	1~40 MHz	40~100 MHz	2 MHz	30-200 MHz	1 MHz	10~100 MHz
	1CT:1CT	-1.1	-16	-10+20*log <sub>10</sub> (f/80MHz)	-42	-15+20*log <sub>10</sub> (f/200 MHz)	-50	-50+22*log <sub>10</sub> (f/10MHz)

#### SCHEMATIC:

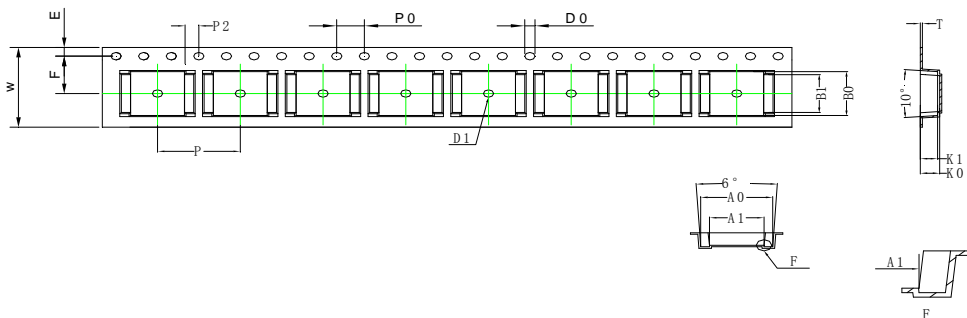


#### DIMENSION: mm

TOLERANCE: (±0.25)



#### Packing:



ITEM	W	A <sub>0</sub>	A <sub>1</sub>	B <sub>0</sub>	B <sub>1</sub>	K <sub>0</sub>	K <sub>1</sub>	E	D <sub>1</sub>	P	F	T
DIM	16.0 <sup>+0.30</sup> <sub>-0.30</sub>	10.45 <sup>+0.10</sup> <sub>-0.10</sub>	7.90 <sup>+0.10</sup> <sub>-0.10</sub>	8.80 <sup>+0.10</sup> <sub>-0.10</sub>	7.60 <sup>+0.10</sup> <sub>-0.10</sub>	2.80 <sup>+0.10</sup> <sub>-0.10</sub>	2.50 <sup>+0.10</sup> <sub>-0.10</sub>	1.75 <sup>+0.10</sup> <sub>-0.10</sub>	1.50 <sup>+0.10</sup> <sub>-0.00</sub>	12.0 <sup>+0.10</sup> <sub>-0.10</sub>	7.50 <sup>+0.10</sup> <sub>-0.10</sub>	0.30 <sup>+0.05</sup> <sub>-0.05</sub>

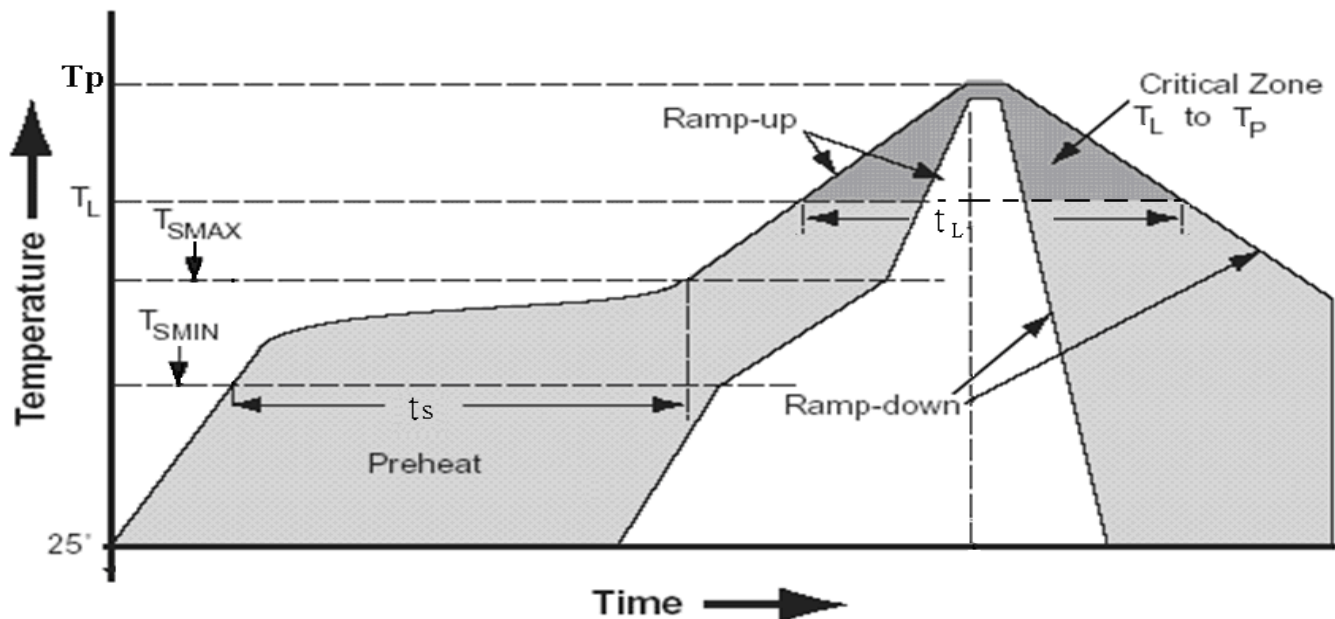
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Solder Reflow profile for Lead-Free packages.  
Package Peak Reflow Temperatures

### Classification Reflow Profiles

Profile Feature	Lead-Free Assembly	
Average ramp-up rate( $T_L$ to $T_P$ )	3°C / Second Max.	
Preheat Temperature Min.( $T_s$ min.) Temperature Max.( $T_s$ max.) Time (min to max) ( $t_s$ )	150 °C 200 °C 60-180 sec	
$T_s$ max. to $T_L$ Ramp-up Rate	3°C / Second Max.	
Time maintained above Temperature ( $T_L$ ) Time ( $t_L$ )	217 °C 60-150 sec	
Peak Temperature ( $T_p$ ) Time within 5 °C of actual peak Temp.	260 +0 / -5 °C 3 to 5 Sec	250 +0 / -5 °C 20 to 40 Sec
Ramp-down	6°C / Second Max.	
Time 25 °C to Peak Temperature	8 minutes Max.	

### Profile



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### PACKING

1. Tape & Reel : 1400pcs / Reel , 7000pcs / Carton
2. Dry Pack : 1pcs  
Product Description:(5g Silica Gel Desiccant)  
PH: 4-8  
Package Materials: Paper(Length 6.5±1cm , Width 5±1cm)
3. Reel Packed By Vacuum  
Reel (Diameter & Height): 33cm\*2.08cm
4. Seal Per JEDEC

